IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re th	ne application of:)
	Hung-Chin Guthrie et al.	Group Art Unit: Unassigned
1 mm1;		Examiner: Unassigned
Applic	cation No. Unassigned) Atty. Docket No. HIT1P057/
5 '1 1	**	HSJ920030250US1
Filed:	Herewith)
For:	ONE STEP COPPER DAMASCENE CMP PROCESS AND SLURRY	Date: February 27, 2004
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 with label number EV395032358US on February 27, 2004.

igned:

Erica L. Farlow

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §§ 1.56 AND 1.97(b)

Mail Stop Patent Application Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§ 1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is believed to be filed before the mailing date of a first Office Action on the merits. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 50-2587 (Order No. <u>HSJ920030250US1/HIT1P057</u>).

Respectfully submitted,

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Form 1449 (Modified)	Atty. Docket No.	Application No.:
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Information Disclosure	Applicant:	
Statement By Applicant	Guthrie et al.	
	Filing Date:	Group Art Unit:
(Use Several Sheets if Necessary)	Herewith	Unassigned

U.S. Patent Documents

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
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	2	2003/0135986	07/24/2003	Eschbach et al.	29	603.12	01/14/2002
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	5	2003/0079416	05/01/2003	Ma et al.	51	307	08/17/2001
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Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication	Country or		Sub-	Trans	lation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	18	2003100678	2003-04-04	JР	H01L	21/304		
	19	2001031953	2001-02-06	JР	C09K	3/14		

Other Documents

Examiner				
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication		
	20	Yoshimizu, H., et al., "Thin Film Magnetic Film Head Composed of Inorganic Materials," IEEE Transactions on Magnetics, Volume 28, No. 5, September 1992		
	21	"Alkaline Formulations for Chemical Mechanical Polishing of Copper Utilizing Azole Passivation", IBM Technical Disclosure Bulletin, October 1994		
	22	"Chemical-Mechanical Polishing of Copper with Ammonium Persulfate", IBM Technical Disclosure Bulletin, October 1994		
	23			
Examiner Date		Date Considered		
L				

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.